

OPERATING PROCEDURES

Karl Suss RA-120 Wafer Scribe

Rev. 1/14/2002

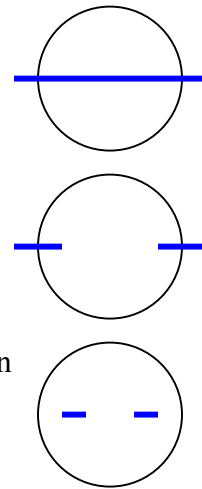
Introduction

The RA-120 Wafer Scribe is comprised of three components:

- Electronics module with power switch
- Display module with soft keypad
- Mechanics module with microscope

The unit has three modes of operation:

- Continuous scribe – scribe is entire length of material
- Edge scribe – scribe length is programmed in 1 micron increments between 20 and 10,000 microns
- Skip scribe – Distance between scribes may be programmed between 20 and 10,000 microns



Pre-Check

1. Plug in vacuum pump located on floor beneath system.
2. Turn on system – power switch is located on left side of electronics module.
3. Rotate brightness control on display module – approximately 10 o'clock position.
4. Wait for display image to stabilize.

Set-Up and Operation

For the set-up, you will need to input the parameters for each of the **5** menu paths:

- **Load wafer** – resets the mechanics and positions stage for loading wafer. Manual p. 2-11.
- **Diamond adjust** – allows tool installation, determines wafer thickness and defines scribe depth. Manual page 2-11.
- **M-scope adjust** – aligns microscope crosshair to wafer geometry. Manual p. 2-14.
- **Pattern set** – defines the wafer axis and wafer area to be scribed. Manual p. 2-17.
- **Define scribe** – coordinates the scribe mode and scribe parameters. Manual p. 2-20.